

8/20/03

PATENT APPLICATION

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FORM PTO-1449	ATTY. DKT NO.	01-244-DIV	SER. NO.
	APPLICANT YAZAKI et al.		
	FILING DATE	August 20, 2003	GROUP

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
MCM	6,207,259	Mar. 27, 2001	Lino et al.	—	—
MCM	6,440,542	Aug. 27, 2002	Kariya	—	—
MCM	5,879,788	Mar. 9, 1999	Fukuta et al.	—	—
MCM	4,795,670	Jan. 3, 1989	Nishigaki et al.	—	—
MCM	5,744,758	Apr. 28, 1998	Takenouchi et al.	—	—
MCM	6,459,046	Oct. 1, 2002	Ochi et al.	—	—
MCM	3,947,956	Apr. 6, 1976	Leroux et al.	—	—
MCM	5,977,490	Nov. 2, 1999	Kawakita et al.	—	—

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUB CLASS	TRANSLATION	
							YES	NO
MCM	JP-A-7-176846 * (Discussed on page 1 of the spec.)	7/14/95	JAPAN	—	—	—	X	
MCM	JP-A-2000-049460 *	2/18/00	JAPAN	—	—	—	X (Abstract)	
MCM	JP-A-2000-138457 *	5/16/00	JAPAN	—	—	—	X (Abstract)	

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER	Mayer	DATE CONSIDERED 10/27/04

12/16/03

* PATENT APPLICATION

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FORM PTO-1449	ATTY. DKT NO.	01-244-DIV	SER. NO.	10/643,919
	APPLICANT YAZAKI et al.			
	FILING DATE	August 20, 2003	GROUP	1775



REFERENCE DESIGNATION

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EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
MCM	4,435,611	Mar. 6, 1984	Ohsawa et al.	—	—
MCM	5,031,308	Jul. 16, 1991	Yamashita et al.	—	—
MCM	5,573,622	Nov. 12, 1996	Hass et al.	—	—
MCM	5,906,042	May 25, 1999	Lan et al.	—	—
MCM	5,972,482	Oct. 26, 1999	Hatakeyama et al.	—	—
MCM	6,000,129	Dec. 14, 1999	Bhatt et al.	—	—
MCM	5,439,164	Aug. 8, 1995	Hasegawa et al.	—	—
MCM	5,551,626	Sep. 3, 1996	Hasegawa et al.	—	—

FOREIGN PATENT DOCUMENTS

								TRANSLATION	
		DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUB CLASS	YES	NO

* Full English text of the JP Document will be available in machine-translated form from JP (Japanese Patent Office) English language web site at <http://www1.ipdl.jpo.go.jp/PA1/cgi-bin/PA1INDEX>.

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

MCM	S.K. Kang et al. "Development of Conductive Adhesive Materials for Via Fill Applications", 2000 Electronic Components and Technology Conference, 2000, pp.887-891
EXAMINER	DATE CONSIDERED
Mayer	10/27/04



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FORM P-100 (Rev. 10/94)	ATTY. DKT NO.	01-244-DIV	SER. NO.	10/643,919
	APPLICANT	YAZAKI et al.		
	FILING DATE	August 20, 2003	GROUP	1775

REFERENCE DESIGNATION

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EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
MCM	5,948,533	09/07/99	Gallagher et al.	—	—
MCM	5,746,868	05/05/98	Abe	—	—
MCM	4,713,494	12/15/87	Oikawa et al.	—	—
MCM	6,143,116	11/07/00	Hayashi et al.	—	—

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUB CLASS	TRANSLATION	
							YES	NO
MCM	JP-A-11-251703	09/17/99	JAPAN	—	—	—	Engl. Abstract	
MCM	EP 0 793 405	09/03/97	EUROPE	—	—	—	X	
MCM	JP-A-11-251751	09/17/99	JAPAN	—	—	—	Engl. Abstract	
MCM	JP-A-11-214575	08/06/99	JAPAN	—	—	—	Engl. Abstract	
MCM	JP-A-2000-236166	08/29/00	JAPAN	—	—	—	Engl. Abstract	

* Full English text of the JP Document will be available in machine-translated form from JP (Japanese Patent Office) English language web site at <http://www1.ipdl.jpo.go.jp/PA1/cgi-bin/PA1INDEX>.

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER	Mayer	DATE CONSIDERED	10/27/04
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